

Description

The 20N06 uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =20 A

 $R_{DS(ON)} < 32m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

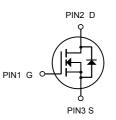
Package Marking and Ordering Information

0	0		
Product ID	Pack	Marking	Qty(PCS)
20N06	TO252-2L	20N06XXXX YYYY	2500

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
Vds	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20		
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	us Drain Current, V _{GS} @ 10V ¹ 20		
I₀@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	ntinuous Drain Current, V _{GS} @ 10V ¹ 10		
Ідм	Pulsed Drain Current ² 80		А	
EAS	Single Pulse Avalanche Energy ³	38		
P₀@Tc=25°C	Total Power Dissipation ⁴	34.7	w	
Тятд	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150 °		





N-Channel MOSFET



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

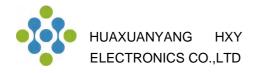
Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics		1			1	1	
Drain-Source Breakdown V	oltage	V _{(BR)DSS}	V_{GS} = 0V, I _D = 250µA	60	-	-	V
Gate-Body Leakage Curren	t	lgss	$V_{DS} = 0V, V_{GS} = \pm 20V$	_	-	±100	nA
Zero Gate Voltage Drain Current	TJ=25℃	ldss	V _{DS} = 60V, V _{GS} = 0V	_	-	1	μA
	TJ=100℃			-	-	100	
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	1.7	2.5	V
Drain-Source on-Resistance ⁴		_	V _{GS} = 10V, I _D = 10A	-	26	32	
		R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	31.5	40	mΩ
Forward Transconductance ⁴		g fs	V _{DS} = 5V, I _D = 10A	-	15.5	-	S
Dynamic Characteristic	:S ⁵				•	•	•
Input Capacitance		Ciss	V _{DS} = 30V, V _{GS} =0V, f =1MHz	-	1355	-	pF
Output Capacitance		Coss		-	60	-	
Reverse Transfer Capacitance		Crss	-	-	49	-	
Gate Resistance		Rg	f =1MHz	-	1.2	-	Ω
Switching Characterist	CS ⁵	·					
Total Gate Charge		Qg		-	22	-	nC
Gate-Source Charge		Q _{gs}	$V_{GS} = 10V, V_{DD} = 30V,$ $I_{D} = 10A$	-	4.2	-	
Gate-Drain Charge	Gate-Drain Charge			-	6.9	-	
Turn-on Delay Time		t _{d(on)}		-	6.4	-	
Rise Time		tr	V _{GS} =10V, V _{DD} = 30V,	-	15.3	-	
Turn-off Delay Time		t _{d(off)}	R _G = 3Ω, I _D = 10A	-	25	-	ns
Fall Time		tr		-	7.6	-	
Body Diode Reverse Recovery Time		trr		-	26	-	ns
Body Diode Reverse Recovery Charge		Qrr	I _F =10A, dl _F /dt=100A/µs	-	45	-	nC
Drain-Source Body Dio	de Characte	ristics				•	
Diode Forward Voltage ⁴		Vsd	Is = 10A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	Tc=25℃	ls	_	_	-	20	Α

Notes:

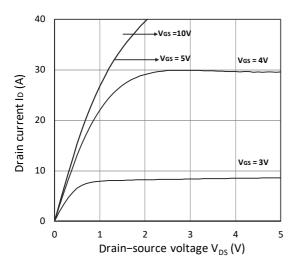
1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}\text{=}150^\circ\text{C}$

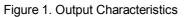
- 2. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25V,\,V_{\text{GS}}\text{=}10V,\,L\text{=}0.4\text{mH},\,I_{\text{AS}}\text{=}14\text{A}$
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

5. This value is guaranteed by design hence it is not included in the production test.



Typical Characteristics





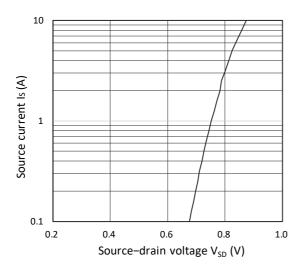


Figure 3. Forward Characteristics of Reverse

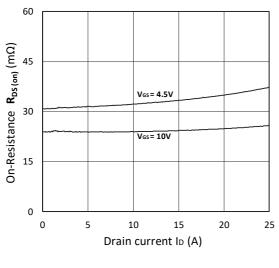


Figure 5. $R_{\text{DS}(\text{ON})}$ vs. I_{D}

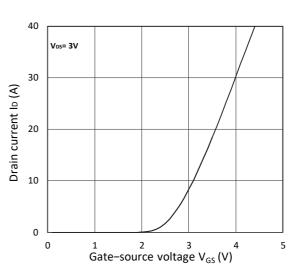
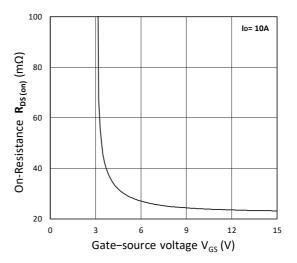


Figure 2. Transfer Characteristics





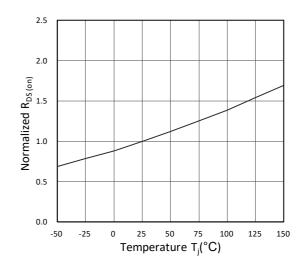
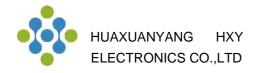


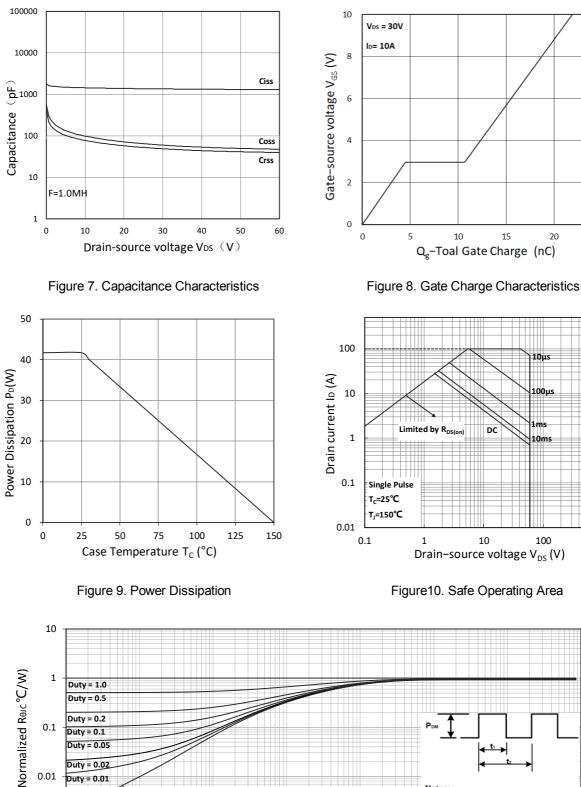
Figure 6. Normalized R_{DS(on)} vs. Temperature



20N06 N-Channel Enhancement Mode MOSFET

25

1000



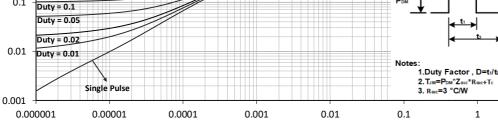


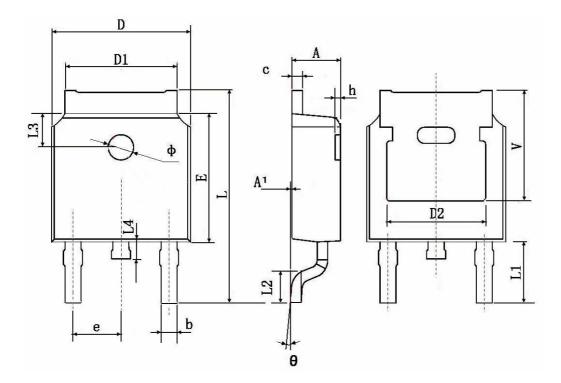
Figure 11. Normalized Maximum Transient Thermal Impedance

t, Pulse Width(S)

10



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0 °	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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